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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Obsolete
Core Processor	M8C
Core Size	8-Bit
Speed	24MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	16
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.4V ~ 5.25V
Data Converters	A/D 8x14b; D/A 2x9b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SOIC (0.295", 7.50mm Width)
Supplier Device Package	20-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy8c24223a-24sxit



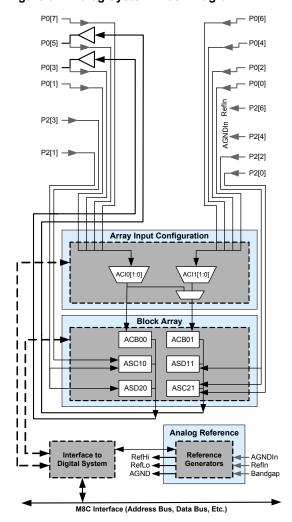
Analog System

The analog system consists of six configurable blocks, each consisting of an opamp circuit that allows the creation of complex analog signal flows. Analog peripherals are very flexible and can be customized to support specific application requirements. Some of the more common PSoC analog functions (most available as user modules) are:

- ADCs (up to two, with 6- to 14-bit resolution, selectable as incremental, delta sigma, and SAR)
- Filters (two and four pole band-pass, low-pass, and notch)
- Amplifiers (up to two, with selectable gain to 48x)
- Instrumentation amplifiers (one with selectable gain to 93x)
- Comparators (up to two, with 16 selectable thresholds)
- DACs (up to two, with 6 to 9-bit resolution)
- Multiplying DACs (up to two, with 6 to 9-bit resolution)
- High current output drivers (two with 30 mA drive as a PSoC Core resource)
- 1.3 V reference (as a system resource)
- DTMF dialer
- Modulators
- Correlators
- Peak detectors
- Many other topologies possible

Analog blocks are arranged in a column of three, which includes one continuous time (CT) and two switched capacitor (SC) blocks, as shown in Figure 3

Figure 3. Analog System Block Diagram





Register Reference

This section lists the registers of the CY8C24x23A PSoC device. For detailed register information, see the PSoC Programmable Sytem-on-Chip Reference Manual.

Register Conventions

Abbreviations Used

The register conventions specific to this section are listed in the following table.

Table 7. Abbreviations

Convention	Description
R	Read register or bit(s)
W	Write register or bit(s)
L	Logical register or bit(s)
С	Clearable register or bit(s)
#	Access is bit specific

Register Mapping Tables

The PSoC device has a total register address space of 512 bytes. The register space is referred to as I/O space and is divided into two banks, Bank 0 and Bank 1. The XOI bit in the Flag register (CPU_F) determines which bank the user is currently in. When the XOI bit is set, the user is in Bank 1.

Note In the following register mapping tables, blank fields are reserved and must not be accessed.



Table 8. Register Map Bank 0 Table: User Space

Name	Addr (0,Hex)		Name	Addr (0,Hex)	Access	Name	Addr (0,Hex)	Access	Name	Addr (0,Hex)	Access
PRT0DR	00	RW		40		ASC10CR0	80	RW		C0	
PRT0IE	01	RW		41		ASC10CR1	81	RW		C1	
PRT0GS	02	RW		42		ASC10CR2	82	RW		C2	
PRT0DM2	03	RW		43		ASC10CR3	83	RW		C3	
PRT1DR	04	RW		44		ASD11CR0	84	RW		C4	
PRT1IE	05	RW		45		ASD11CR1	85	RW		C5	
PRT1GS	06	RW		46		ASD11CR2	86	RW		C6	
PRT1DM2	07	RW		47		ASD11CR3	87	RW		C7	
PRT2DR	08	RW		48			88			C8	
PRT2IE	09	RW		49			89			C9	
PRT2GS	0A	RW		4A			8A			CA	
PRT2DM2	0B	RW		4B			8B			СВ	
	0C			4C			8C			CC	
	0D			4D			8D			CD	
	0E			4E			8E			CE	
	0F			4F			8F			CF	
	10			50		ASD20CR0	90	RW		D0	
	11			51		ASD20CR1	91	RW		D1	
	12			52		ASD20CR2	92	RW		D2	
	13			53		ASD20CR3	93	RW		D3	
	14			54		ASC21CR0	94	RW		D4	
	15			55		ASC21CR1	95	RW		D5	
	16			56		ASC21CR2	96	RW	I2C_CFG	D6	RW
	17			57		ASC21CR3	97	RW	I2C SCR	D7	#
	18			58		7100210110	98	1444	I2C_DR	D8	RW
	19			59			99		I2C MSCR	D9	#
	1A			5A			9A		INT_CLR0	DA	RW
	1B			5B			9B		INT_CLR1	DB	RW
	1C			5C			9C		INT_CLKT	DC	KVV
	1D			5D			9D		INT_CLR3	DD	RW
	1E			5E			9E		INT_CERS	DE	RW
	1F						9F		IIVI_IVISKS	DF	IXVV
DDDOODDO		ш	ANAV INI	5F	DW				INIT MOKO	E0	DW
DBB00DR0	20	#	AMX_IN	60	RW		A0		INT_MSK0		RW
DBB00DR1	21	W		61			A1		INT_MSK1	E1	RW
DBB00DR2	22	RW	ADE OD	62	DW		A2		INT_VC	E2	RC
DBB00CR0	23	#	ARF_CR	63	RW		A3		RES_WDT	E3	W
DBB01DR0	24	#	CMP_CR0	64	#		A4		DEC_DH	E4	RC
DBB01DR1	25	W	ASY_CR	65	#		A5		DEC_DL	E5	RC
DBB01DR2	26	RW	CMP_CR1	66	RW		A6		DEC_CR0	E6	RW
DBB01CR0	27	#		67			A7		DEC_CR1	E7	RW
DCB02DR0	28	#		68			A8		MUL_X	E8	W
DCB02DR1	29	W		69			A9		MUL_Y	E9	W
DCB02DR2	2A	RW		6A			AA		MUL_DH	EA	R
DCB02CR0	2B	#		6B			AB		MUL_DL	EB	R
DCB03DR0	2C	#		6C			AC		ACC_DR1	EC	RW
DCB03DR1	2D	W		6D			AD		ACC_DR0	ED	RW
DCB03DR2	2E	RW		6E			AE		ACC_DR3	EE	RW
DCB03CR0	2F	#		6F			AF		ACC_DR2	EF	RW
	30		ACB00CR3	70	RW	RDI0RI	B0	RW		F0	
	31		ACB00CR0	71	RW	RDI0SYN	B1	RW		F1	
	32		ACB00CR1	72	RW	RDI0IS	B2	RW		F2	
	33		ACB00CR2	73	RW	RDI0LT0	B3	RW		F3	
	34		ACB01CR3	74	RW	RDI0LT1	B4	RW		F4	
	35		ACB01CR0	75	RW	RDI0RO0	B5	RW		F5	
	36		ACB01CR1	76	RW	RDI0RO1	B6	RW		F6	
	37		ACB01CR2	77	RW		B7		CPU_F	F7	RL
	38			78			B8			F8	
	39			79			B9			F9	
	3A			7A			BA			FA	
	3B			7B			BB			FB	
	3C			7C			BC			FC	
	3D			7D			BD			FD	
	3E			7E			BE		CPU SCR1	FE	#
	3F			7F			BF		CPU SCR0	FF	#

Blank fields are Reserved and must not be accessed.

Access is bit specific.



Table 15. 3.3-V DC Operational Amplifier Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
V _{OSOA}	Input offset voltage (absolute value) Power = low, Opamp bias = high Power = medium, Opamp bias = high Power = high, Opamp bias = high	- - -	1.65 1.32 –	10 8 -	mV mV mV	Power = high, Opamp bias = high setting is not allowed for 3.3 V V_{DD} operation.
TCV _{OSOA}	Average input offset voltage drift	-	7.0	35.0	μV/°C	
I _{EBOA}	Input leakage current (port 0 analog pins)	-	20	-	pА	Gross tested to 1 μA
C _{INOA}	Input capacitance (port 0 analog pins)		4.5	9.5	pF	Package and pin dependent. Temp = 25 °C
V _{CMOA}	Common mode voltage range	0.2	-	V _{DD} – 0.2	V	The common-mode input voltage range is measured through an analog output buffer. The specification includes the limitations imposed by the characteristics of the analog output buffer.
G _{OLOA}	Open loop gain Power = low, ppamp Opamp bias = low Power = medium, Opamp bias = low Power = high, Opamp bias = low	60 60 80	_ _ _	- - -	dB dB dB	Specification is applicable at low Opamp bias. For high Opamp bias mode (except high power, high Opamp bias), minimum is 60 dB.
V _{OHIGHOA}	High output voltage swing (internal signals) Power = low, Opamp bias = low Power = medium, Opamp bias = low Power = high, Opamp bias = low	V _{DD} - 0.2 V _{DD} - 0.2 V _{DD} - 0.2	_ _ _	- - -	V V V	Power = high, Opamp bias = high setting is not allowed for 3.3 V V _{DD} operation.
V _{OLOWOA}	Low output voltage swing (internal signals) Power = low, ppamp Opamp bias = low Power = medium, Opamp bias = low Power = high, Opamp bias = low	- - -	_ _ _	0.2 0.2 0.2	V V	Power = high, Opamp bias = high setting is not allowed for 3.3 V V _{DD} operation.
Isoa	Supply current (including associated AGND buffer) Power = low, Opamp bias = low Power = low, Opamp bias = high Power = medium, Opamp bias = low Power = medium, Opamp bias = high Power = high, Opamp bias = low Power = high, Opamp bias = high		150 300 600 1200 2400	200 400 800 1600 3200	µА µА µА µА µА	Power = high, Opamp bias = high setting is not allowed for 3.3 V V _{DD} operation.
PSRR _{OA}	Supply voltage rejection ratio	64	80	-	dB	$V_{SS} \le V_{IN} \le (V_{DD} - 2.25)$ or $(V_{DD} - 1.25 \ V) \le V_{IN} \le V_{DD}$



DC Switch Mode Pump Specifications

Table 21 lists the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and $-40~^{\circ}\text{C} \le T_{A} \le 85~^{\circ}\text{C}$, 3.0 V to 3.6 V and $-40~^{\circ}\text{C} \le T_{A} \le 85~^{\circ}\text{C}$, or 2.4 V to 3.0 V and $-40~^{\circ}\text{C} \le T_{A} \le 85~^{\circ}\text{C}$, respectively. Typical parameters are measured at 5 V, 3.3 V, and 2.7 V at 25 $^{\circ}\text{C}$ and are for design guidance only.

Table 21. DC Switch Mode Pump (SMP) Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
V _{PUMP} 5 V	5 V output voltage from pump	4.75	5.0	5.25	V	Configuration listed in footnote. ^[11] Average, neglecting ripple. SMP trip voltage is set to 5.0 V.
V _{PUMP} 3 V	3.3 V output voltage from pump	3.00	3.25	3.60	V	Configuration listed in footnote. [11] Average, neglecting ripple. SMP trip voltage is set to 3.25 V.
V _{PUMP} 2 V	2.6 V output voltage from pump	2.45	2.55	2.80	V	Configuration listed in footnote. [11] Average, neglecting ripple. SMP trip voltage is set to 2.55 V.
I _{PUMP}		5 8 8		- - -	mA mA mA	Configuration listed in footnote. [11] SMP trip voltage is set to 5.0 V. SMP trip voltage is set to 3.25 V. SMP trip voltage is set to 2.55 V.
V _{BAT} 5 V	Input voltage range from battery	1.8	_	5.0	V	Configuration listed in footnote. ^[11] SMP trip voltage is set to 5.0 V.
V _{BAT} 3 V	Input voltage range from battery	1.0	_	3.3	V	Configuration listed in footnote. ^[11] SMP trip voltage is set to 3.25 V.
V _{BAT} 2 V	Input voltage range from battery	1.0	_	3.0	V	Configuration listed in footnote. ^[11] SMP trip voltage is set to 2.55 V.
V _{BATSTART}	Minimum input voltage from battery to start pump	1.2	-	-	V	Configuration listed in footnote. $^{[11]}$ 0 °C \leq T _A \leq 100. 1.25 V at T _A = -40 °C
ΔV _{PUMP_Line}	Line regulation (over V _{BAT} range)	-	5	-	%V _O	Configuration listed in footnote. [11] V _O is the V _{DD} Value for PUMP Trip" specified by the VM[2:0] setting in the DC POR and LVD Specification, Table 26 on page 35.
ΔV _{PUMP_Load}	Load regulation	-	5	-	%V _O	Configuration listed in footnote. [11] V_O is the " V_{DD} value for PUMP Trip" specified by the VM[2:0] setting in the DC POR and LVD Specification, Table 26 on page 35.
ΔV_{PUMP_Ripple}	Output voltage ripple (depends on capacitor/load)	_	100	_	mVpp	Configuration listed in footnote. ^[11] Load is 5 mA.
E ₃	Efficiency	35	50	-	%	Configuration listed in footnote. ^[11] Load is 5 mA. SMP trip voltage is set to 3.25 V.
E ₂	Efficiency	-	_	ı		
F _{PUMP}	Switching frequency	-	1.3	_	MHz	
DC _{PUMP}	Switching duty cycle		50		%	



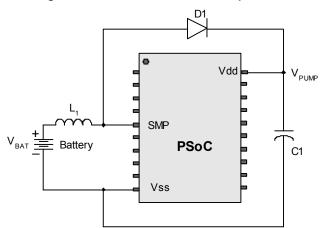


Figure 10. Basic Switch Mode Pump Circuit



Table 22. 5-V DC Analog Reference Specifications (continued)

Reference ARF_CR [5:3]	Reference Power Settings	Symbol	Reference	Description	Min	Тур	Max	Units
0b010	RefPower = high	V _{REFHI}	Ref High	V_{DD}	V _{DD} – 0.121	V _{DD} – 0.003	V _{DD}	V
	Opamp bias = high	V_{AGND}	AGND	V _{DD} /2	V _{DD} /2 – 0.040	V _{DD} /2	$V_{DD}/2 + 0.034$	V
		V_{REFLO}	Ref Low	V _{SS}	V _{SS}	V _{SS} + 0.006	V _{SS} + 0.019	V
	RefPower = high	V_{REFHI}	Ref High	V_{DD}	V _{DD} – 0.083	V _{DD} – 0.002	V_{DD}	V
	Opamp bias = low	V_{AGND}	AGND	V _{DD} /2	V _{DD} /2 – 0.040	V _{DD} /2 – 0.001	$V_{DD}/2 + 0.033$	V
		V_{REFLO}	Ref Low	V _{SS}	V _{SS}	V _{SS} + 0.004	V _{SS} + 0.016	V
	RefPower = medium Opamp bias = high	V _{REFHI}	Ref High	V_{DD}	V _{DD} – 0.075	V _{DD} – 0.002	V_{DD}	V
		V _{AGND}	AGND	V _{DD} /2	V _{DD} /2 – 0.040	V _{DD} /2 – 0.001	$V_{DD}/2 + 0.032$	V
		V _{REFLO}	Ref Low	V _{SS}	V _{SS}	V _{SS} + 0.003	V _{SS} + 0.015	V
	RefPower = medium	V _{REFHI}	Ref High	V_{DD}	V _{DD} – 0.074	V _{DD} – 0.002	V_{DD}	V
	Opamp bias = low	V _{AGND}	AGND	V _{DD} /2	V _{DD} /2 – 0.040	V _{DD} /2 – 0.001	V _{DD} /2 + 0.032	V
		V _{REFLO}	Ref Low	V _{SS}	V _{SS}	V _{SS} + 0.002	V _{SS} + 0.014	V
0b011	RefPower = high	V _{REFHI}	Ref High	3 × Bandgap	3.753	3.874	3.979	V
	Opamp bias = high	V _{AGND}	AGND	2 × Bandgap	2.511	2.590	2.657	V
		V _{REFLO}	Ref Low	Bandgap	1.243	1.297	1.333	V
	RefPower = high	V _{REFHI}	Ref High	3 × Bandgap	3.767	3.881	3.974	V
	Opamp bias = low	V _{AGND}	AGND	2 × Bandgap	2.518	2.592	2.652	V
		V _{REFLO}	Ref Low	Bandgap	1.241	1.295	1.330	V
	RefPower = medium	V _{REFHI}	Ref High	3 × Bandgap	2.771	3.885	3.979	V
	Opamp bias = high	V _{AGND}	AGND	2 × Bandgap	2.521	2.593	2.649	V
		V _{REFLO}	Ref Low	Bandgap	1.240	1.295	1.331	V
	RefPower = medium Opamp bias = low	V _{REFHI}	Ref High	3 × Bandgap	3.771	3.887	3.977	V
		V _{AGND}	AGND	2 × Bandgap	2.522	2.594	2.648	V
		V _{REFLO}	Ref Low	Bandgap	1.239	1.295	1.332	V
0b100	RefPower = high Opamp bias = high	V _{REFHI}	Ref High	2 × Bandgap + P2[6] (P2[6] = 1.3 V)	2.481 + P2[6]	2.569 + P2[6]	2.639 + P2[6]	V
		V _{AGND}	AGND	2 × Bandgap	2.511	2.590	2.658	V
		V _{REFLO}	Ref Low	2 × Bandgap – P2[6] (P2[6] = 1.3 V)	2.515 – P2[6]	2.602 - P2[6]	2.654 - P2[6]	V
	RefPower = high Opamp bias = low	V_{REFHI}	Ref High	2 × Bandgap + P2[6] (P2[6] = 1.3 V)	2.498 + P2[6]	2.579 + P2[6]	2.642 + P2[6]	V
		V_{AGND}	AGND	2 × Bandgap	2.518	2.592	2.652	V
		V _{REFLO}	Ref Low	2 × Bandgap – P2[6] (P2[6] = 1.3 V)	2.513 – P2[6]	2.598 - P2[6]	2.650 - P2[6]	V
	RefPower = medium Opamp bias = high	V_{REFHI}	Ref High	2 × Bandgap + P2[6] (P2[6] = 1.3 V)	2.504 + P2[6]	2.583 + P2[6]	2.646 + P2[6]	V
		V_{AGND}	AGND	2 × Bandgap	2.521	2.592	2.650	V
		V _{REFLO}	Ref Low	2 × Bandgap – P2[6] (P2[6] = 1.3 V)	2.513 – P2[6]	2.596 - P2[6]	2.649 - P2[6]	V
	RefPower = medium Opamp bias = low	V_{REFHI}	Ref High	2 × Bandgap + P2[6] (P2[6] = 1.3 V)	2.505 + P2[6]	2.586 + P2[6]	2.648 + P2[6]	V
		V_{AGND}	AGND	2 × Bandgap	2.521	2.594	2.648	V
		V _{REFLO}	Ref Low	2 × Bandgap – P2[6] (P2[6] = 1.3 V)	2.513 – P2[6]	2.595 – P2[6]	2.648 – P2[6]	V



Table 22. 5-V DC Analog Reference Specifications (continued)

Reference								
ARF_CR [5:3]	Reference Power Settings	Symbol	Reference	Description	Min	Тур	Max	Units
0b101	RefPower = high Opamp bias = high	V _{REFHI}	Ref High	P2[4] + Bandgap (P2[4] = V _{DD} /2)	P2[4] + 1.228	P2[4] + 1.284	P2[4] + 1.332	V
		V_{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	-
		V _{REFLO}	Ref Low	P2[4] – Bandgap (P2[4] = V _{DD} /2)	P2[4] – 1.358	P2[4] – 1.293	P2[4] – 1.226	V
	RefPower = high Opamp bias = low	V _{REFHI}	Ref High	P2[4] + Bandgap (P2[4] = V _{DD} /2)	P2[4] + 1.236	P2[4] + 1.289	P2[4] + 1.332	V
		V _{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	-
		V_{REFLO}	Ref Low	P2[4] - Bandgap (P2[4] = $V_{DD}/2$)	P2[4] – 1.357	P2[4] – 1.297	P2[4] - 1.229	V
	RefPower = medium Opamp bias = high	V _{REFHI}	Ref High	P2[4] + Bandgap (P2[4] = V _{DD} /2)	P2[4] + 1.237	P2[4] + 1.291	P2[4] + 1.337	V
		V_{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	-
		V _{REFLO}	Ref Low	P2[4] - Bandgap (P2[4] = $V_{DD}/2$)	P2[4] – 1.356	P2[4] – 1.299	P2[4] – 1.232	V
	RefPower = medium Opamp bias = low	V_{REFHI}	Ref High	P2[4] + Bandgap (P2[4] = $V_{DD}/2$)	P2[4] + 1.237	P2[4] + 1.292	P2[4] + 1.337	V
		V _{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	-
		V_{REFLO}	Ref Low	P2[4] - Bandgap (P2[4] = $V_{DD}/2$)	P2[4] – 1.357	P2[4] – 1.300	P2[4] – 1.233	V
0b110	RefPower = high	V _{REFHI}	Ref High	2 × Bandgap	2.512	2.594	2.654	V
	Opamp bias = high	V_{AGND}	AGND	Bandgap	1.250	1.303	1.346	V
		V_{REFLO}	Ref Low	V_{SS}	V _{SS}	$V_{SS} + 0.011$	$V_{SS} + 0.027$	V
	RefPower = high	V_{REFHI}	Ref High	2 × Bandgap	2.515	2.592	2.654	V
	Opamp bias = low	V_{AGND}	AGND	Bandgap	1.253	1.301	1.340	V
		V_{REFLO}	Ref Low	V_{SS}	V _{SS}	$V_{SS} + 0.006$	$V_{SS} + 0.02$	V
	RefPower = medium	V_{REFHI}	Ref High	2 × Bandgap	2.518	2.593	2.651	V
	Opamp bias = high	V_{AGND}	AGND	Bandgap	1.254	1.301	1.338	٧
		V_{REFLO}	Ref Low	V_{SS}	V _{SS}	$V_{SS} + 0.004$	$V_{SS} + 0.017$	V
	RefPower = medium	V_{REFHI}	Ref High	2 × Bandgap	2.517	2.594	2.650	V
	Opamp bias = low	V _{AGND}	AGND	Bandgap	1.255	1.300	1.337	V
		V _{REFLO}	Ref Low	V _{SS}	V _{SS}	V _{SS} + 0.003	V _{SS} + 0.015	V
0b111	RefPower = high	V _{REFHI}	Ref High	3.2 × Bandgap	4.011	4.143	4.203	V
	Opamp bias = high	V _{AGND}	AGND	1.6 × Bandgap	2.020	2.075	2.118	V
		V _{REFLO}	Ref Low	V _{SS}	V _{SS}	V _{SS} + 0.011	V _{SS} + 0.026	V
	RefPower = high	V _{REFHI}	Ref High	3.2 × Bandgap	4.022	4.138	4.203	V
	Opamp bias = low	V_{AGND}	AGND	1.6 × Bandgap	2.023	2.075	2.114	V
		V_{REFLO}	Ref Low	V _{SS}	V _{SS}	V _{SS} + 0.006	V _{SS} + 0.017	V
	RefPower = medium	V_{REFHI}	Ref High	3.2 × Bandgap	4.026	4.141	4.207	V
	Opamp bias = high	V_{AGND}	AGND	1.6 × Bandgap	2.024	2.075	2.114	V
		V_{REFLO}	Ref Low	V _{SS}	V _{SS}	V _{SS} + 0.004	V _{SS} + 0.015	V
	RefPower = medium	V _{REFHI}	Ref High	3.2 × Bandgap	4.030	4.143	4.206	V
	Opamp bias = low	V_{AGND}	AGND	1.6 × Bandgap	2.024	2.076	2.112	V
		V_{REFLO}	Ref Low	V _{SS}	V _{SS}	$V_{SS} + 0.003$	V _{SS} + 0.013	V



Table 23. 3.3-V DC Analog Reference Specifications

Reference ARF_CR [5:3]	Reference Power Settings	Symbol	Reference	Description	Min	Тур	Max	Units
0b000	RefPower = high	V _{REFHI}	Ref High	V _{DD} /2 + Bandgap	V _{DD} /2 + 1.170	V _{DD} /2 + 1.288	V _{DD} /2 + 1.376	V
	Opamp bias = high	V _{AGND}	AGND	V _{DD} /2	$V_{DD}/2 - 0.098$	$V_{DD}/2 + 0.003$	$V_{DD}/2 + 0.097$	V
		V _{REFLO}	Ref Low	V _{DD} /2 – Bandgap	V _{DD} /2 – 1.386	V _{DD} /2 – 1.287	V _{DD} /2 – 1.169	V
	RefPower = high	V _{REFHI}	Ref High	V _{DD} /2 + Bandgap	V _{DD} /2 + 1.210	V _{DD} /2 + 1.290	V _{DD} /2 + 1.355	V
	Opamp bias = low	V _{AGND}	AGND	V _{DD} /2	$V_{DD}/2 - 0.055$	V _{DD} /2 + 0.001	$V_{DD}/2 + 0.054$	V
		V _{REFLO}	Ref Low	V _{DD} /2 – Bandgap	V _{DD} /2 – 1.359	V _{DD} /2 – 1.292	V _{DD} /2 – 1.214	V
	RefPower = medium	V_{REFHI}	Ref High	V _{DD} /2 + Bandgap	V _{DD} /2 + 1.198	V _{DD} /2 + 1.292	V _{DD} /2 + 1.368	V
	Opamp bias = high	V _{AGND}	AGND	V _{DD} /2	V _{DD} /2 – 0.041	V _{DD} /2	$V_{DD}/2 + 0.04$	V
		V _{REFLO}	Ref Low	V _{DD} /2 – Bandgap	V _{DD} /2 – 1.362	V _{DD} /2 – 1.295	V _{DD} /2 – 1.220	V
	RefPower = medium	V_{REFHI}	Ref High	V _{DD} /2 + Bandgap	V _{DD} /2 + 1.202	V _{DD} /2 + 1.292	V _{DD} /2 + 1.364	V
	Opamp bias = low	V _{AGND}	AGND	V _{DD} /2	$V_{DD}/2 - 0.033$	V _{DD} /2	$V_{DD}/2 + 0.030$	V
		V_{REFLO}	Ref Low	V _{DD} /2 – Bandgap	V _{DD} /2 – 1.364	V _{DD} /2 – 1.297	V _{DD} /2 – 1.222	V
0b001	RefPower = high Opamp bias = high	V_{REFHI}	Ref High	P2[4]+P2[6] (P2[4] = V _{DD} /2, P2[6] = 0.5 V)	P2[4] + P2[6] - 0.072	P2[4] + P2[6] - 0.017	P2[4] + P2[6] + 0.041	V
		V _{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	-
		V _{REFLO}	Ref Low	P2[4]–P2[6] (P2[4] = V _{DD} /2, P2[6] = 0.5 V)	P2[4] – P2[6] – 0.029	P2[4]-P2[6]+ 0.010	P2[4]-P2[6]+ 0.048	V
	RefPower = high Opamp bias = low	V _{REFHI}	Ref High	P2[4]+P2[6] (P2[4] = V _{DD} /2, P2[6] = 0.5 V)	P2[4] + P2[6] - 0.066	P2[4] + P2[6] – 0.010	P2[4] + P2[6] + 0.043	V
		V _{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	-
		V _{REFLO}	Ref Low	P2[4]–P2[6] (P2[4] = V _{DD} /2, P2[6] = 0.5 V)	P2[4] – P2[6] – 0.024	P2[4]-P2[6]+ 0.004	P2[4]-P2[6]+ 0.034	V
	RefPower = medium Opamp bias = high	V _{REFHI}	Ref High	P2[4]+P2[6] (P2[4] = V _{DD} /2, P2[6] = 0.5 V)	P2[4] + P2[6] - 0.073	P2[4] + P2[6] – 0.007	P2[4] + P2[6] + 0.053	V
		V _{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	-
		V _{REFLO}	Ref Low	P2[4]–P2[6] (P2[4] = V _{DD} /2, P2[6] = 0.5 V)	P2[4] – P2[6] – 0.028	P2[4]-P2[6]+ 0.002	P2[4]-P2[6]+ 0.033	V
	RefPower = medium Opamp bias = low	V _{REFHI}	Ref High	P2[4]+P2[6] (P2[4] = V _{DD} /2, P2[6] = 0.5 V)	P2[4] + P2[6] - 0.073	P2[4] + P2[6] – 0.006	P2[4] + P2[6] + 0.056	V
		V_{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	_
		V_{REFLO}	Ref Low	P2[4]–P2[6] (P2[4] = V _{DD} /2, P2[6] = 0.5 V)	P2[4] – P2[6] – 0.030	P2[4] – P2[6]	P2[4]-P2[6]+ 0.032	V
0b010	RefPower = high	V _{REFHI}	Ref High	V_{DD}	V _{DD} – 0.102	V _{DD} – 0.003	V_{DD}	V
	Opamp bias = high	V _{AGND}	AGND	V _{DD} /2	V _{DD} /2 – 0.040	V _{DD} /2 + 0.001	$V_{DD}/2 + 0.039$	V
		V _{REFLO}	Ref Low	V _{SS}	V _{SS}	V _{SS} + 0.005	V _{SS} + 0.020	V
	RefPower = high	V _{REFHI}	Ref High	V_{DD}	V _{DD} – 0.082	V _{DD} – 0.002	V_{DD}	V
	Opamp bias = Tow	V _{AGND}	AGND	V _{DD} /2	$V_{DD}/2 - 0.031$	V _{DD} /2	$V_{DD}/2 + 0.028$	V
		V _{REFLO}	Ref Low	V _{SS}	V _{SS}	V _{SS} + 0.003	V _{SS} + 0.015	V
	RefPower = medium	V_{REFHI}	Ref High	V_{DD}	V _{DD} – 0.083	V _{DD} – 0.002	V_{DD}	V
	Opamp bias = high	V _{AGND}	AGND	V _{DD} /2	$V_{DD}/2 - 0.032$	V _{DD} /2 – 0.001	$V_{DD}/2 + 0.029$	V
		V_{REFLO}	Ref Low	V _{SS}	V _{SS}	V _{SS} + 0.002	V _{SS} + 0.014	V
	RefPower = medium	V_{REFHI}	Ref High	V_{DD}	V _{DD} – 0.081	V _{DD} – 0.002	V_{DD}	V
	Opamp bias = low	V_{AGND}	AGND	V _{DD} /2	$V_{DD}/2 - 0.033$	V _{DD} /2 – 0.001	V _{DD} /2 + 0.029	V
		V _{REFLO}	Ref Low	V _{SS}	V _{SS}	V _{SS} + 0.002	V _{SS} + 0.013	V
0b011	All power settings Not allowed at 3.3 V	-	-	_	_	_	_	_



Table 23. 3.3-V DC Analog Reference Specifications (continued)

Reference ARF_CR [5:3]	Reference Power Settings	Symbol	Reference	Description	Min	Тур	Max	Units
0b100	All power settings Not allowed at 3.3 V	-	_	_	_	_	_	_
0b101	RefPower = high Opamp bias = high	V _{REFHI}	Ref High	P2[4] + Bandgap (P2[4] = V _{DD} /2)	P2[4] + 1.211	P2[4] + 1.285	P2[4] + 1.348	V
		V_{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	-
		V _{REFLO}	Ref Low	P2[4] – Bandgap (P2[4] = V _{DD} /2)	P2[4] - 1.354	P2[4] - 1.290	P2[4] – 1.197	V
	RefPower = high Opamp bias = low	V_{REFHI}	Ref High	P2[4] + Bandgap (P2[4] = V _{DD} /2)	P2[4] + 1.209	P2[4] + 1.289	P2[4] + 1.353	V
		V_{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	-
		V_{REFLO}	Ref Low	P2[4] – Bandgap (P2[4] = V _{DD} /2)	P2[4] – 1.352	P2[4] – 1.294	P2[4] – 1.222	V
	RefPower = medium Opamp bias = high	V _{REFHI}	Ref High	P2[4] + Bandgap (P2[4] = V _{DD} /2)	P2[4] + 1.218	P2[4] + 1.291	P2[4] + 1.351	V
		V_{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	-
		V _{REFLO}	Ref Low	P2[4] – Bandgap (P2[4] = V _{DD} /2)	P2[4] - 1.351	P2[4] - 1.296	P2[4] - 1.224	V
	RefPower = medium Opamp bias = low	V _{REFHI}	Ref High	P2[4] + Bandgap (P2[4] = V _{DD} /2)	P2[4] + 1.215	P2[4] + 1.292	P2[4] + 1.354	V
		V_{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	-
		V _{REFLO}	Ref Low	P2[4] – Bandgap (P2[4] = V _{DD} /2)	P2[4] - 1.352	P2[4] – 1.297	P2[4] - 1.227	V
0b110	RefPower = high	V_{REFHI}	Ref High	2 × Bandgap	2.460	2.594	2.695	٧
	Opamp bias = high	V_{AGND}	AGND	Bandgap	1.257	1.302	1.335	V
		V_{REFLO}	Ref Low	V _{SS}	V _{SS}	V _{SS} + 0.01	V _{SS} + 0.029	V
	RefPower = high Opamp bias = low	V_{REFHI}	Ref High	2 × Bandgap	2.462	2.592	2.692	V
	Opamp bias = low	V_{AGND}	AGND	Bandgap	1.256	1.301	1.332	V
		V_{REFLO}	Ref Low	V _{SS}	V_{SS}	$V_{SS} + 0.005$	V _{SS} + 0.017	V
	RefPower = medium	V_{REFHI}	Ref High	2 × Bandgap	2.473	2.593	2.682	V
	Opamp bias = high	V_{AGND}	AGND	Bandgap	1.257	1.301	1.330	V
		V_{REFLO}	Ref Low	V _{SS}	V _{SS}	$V_{SS} + 0.003$	V _{SS} + 0.014	V
	RefPower = medium Opamp bias = low	V_{REFHI}	Ref High	2 × Bandgap	2.470	2.594	2.685	V
		V_{AGND}	AGND	Bandgap	1.256	1.300	1.332	V
		V_{REFLO}	Ref Low	V _{SS}	V _{SS}	V _{SS} + 0.002	V _{SS} + 0.012	V
0b111	All power settings Not allowed at 3.3 V	-	_	_	_	_	_	_



AC Operational Amplifier Specifications

The following tables list the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C \leq T_A \leq 85 °C, 3.0 V to 3.6 V and –40 °C \leq T_A \leq 85 °C, or 2.4 V to 3.0 V and –40 °C \leq T_A \leq 85 °C, respectively. Typical parameters are measured at 5 V, 3.3 V, and 2.7 V at 25 °C and are for design guidance only.

Settling times, slew rates, and gain bandwidth are based on the analog continuous time PSoC block.

Power = high and Opamp bias = high is not supported at 3.3 V and 2.7 V.

Table 33. 5-V AC Operational Amplifier Specifications

Symbol	Description	Min	Тур	Max	Units
t _{ROA}	Rising settling time from 80% of ΔV to 0.1% of ΔV (10 pF load, unity gain) Power = low, Opamp bias = low Power = medium, Opamp bias = high Power = high, Opamp bias = high	- - -	_ _ _	3.9 0.72 0.62	μs μs μs
t _{SOA}	Falling settling time from 20% of ΔV to 0.1% of ΔV (10 pF load, unity gain) Power = low, Opamp bias = low Power = medium, Opamp bias = high Power = high, Opamp bias = high	- - -	_ _ _	5.9 0.92 0.72	μs μs μs
SR _{ROA}	Rising slew rate (20% to 80%) (10 pF load, unity gain) Power = low, Opamp bias = low Power = medium, Opamp bias = high Power = high, Opamp bias = high	0.15 1.7 6.5	- - -	- - -	V/μs V/μs V/μs
SR _{FOA}	Falling slew rate (20% to 80%) (10 pF load, unity gain) Power = low, Opamp bias = low Power = medium, Opamp bias = high Power = high, Opamp bias = high	0.01 0.5 4.0	- - -	- - -	V/μs V/μs V/μs
BW _{OA}	Gain bandwidth product Power = low, Opamp bias = low Power = medium, Opamp bias = high Power = high, Opamp bias = high	0.75 3.1 5.4	_ _ _	- - -	MHz MHz MHz
E _{NOA}	Noise at 1 kHz (Power = medium, Opamp bias = high)	_	100	_	nV/rt-Hz

Table 34. 3.3-V AC Operational Amplifier Specifications

Symbol	Description	Min	Тур	Max	Units
t _{ROA}	Rising settling time from 80% of ΔV to 0.1% of ΔV (10 pF load, unity gain) Power = low, Opamp bias = low Power = medium, Opamp bias = high		- -	3.92 0.72	μs μs
t _{SOA}	Falling settling time from 20% of ΔV to 0.1% of ΔV (10 pF load, unity gain) Power = low, Opamp bias = low Power = medium, Opamp bias = high			5.41 0.72	μs μs
SR _{ROA}	Rising slew rate (20% to 80%) (10 pF load, unity gain) Power = low, Opamp bias = low Power = medium, Opamp bias = high	0.31 2.7	_ _	<u>-</u>	V/µs V/µs
SR _{FOA}	Falling slew rate (20% to 80%) (10 pF load, unity gain) Power = low, Opamp bias = low Power = medium, Opamp bias = high	0.24 1.8	_ _	_ _	V/µs V/µs
BW _{OA}	Gain bandwidth product Power = low, Opamp bias = low Power = medium, Opamp bias = high	0.67 2.8	_ _	_ _	MHz MHz
E _{NOA}	Noise at 1 kHz (Power = medium, Opamp bias = high)	-	100	-	nV/rt-Hz



Table 41. 2.7-V AC Analog Output Buffer Specifications

Symbol	Description	Min	Тур	Max	Units
t _{ROB}	Rising settling time to 0.1%, 1 V Step, 100 pF load Power = low Power = high		_ _	4 4	μs μs
t _{SOB}	Falling settling time to 0.1%, 1 V Step, 100 pF load Power = low Power = high	_ _	_ _	3 3	μs μs
SR _{ROB}	Rising slew rate (20% to 80%), 1 V Step, 100 pF load Power = low Power = high	0.4 0.4	<u>-</u>	<u>-</u> -	V/µs V/µs
SR _{FOB}	Falling slew rate (80% to 20%), 1 V Step, 100 pF load Power = low Power = high	0.4 0.4	_ _	_ _ _	V/µs V/µs
BW _{OB}	Small signal bandwidth, 20 mV _{pp} , 3dB BW, 100 pF load Power = low Power = high	0.6 0.6	_ _	_ _ _	MHz MHz
BW _{OB}	Large signal bandwidth, 1 V _{pp} , 3dB BW, 100 pF load Power = low Power = high	180 180	<u>-</u>	<u>-</u> -	kHz kHz

AC External Clock Specifications

The following tables list the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and $-40~^{\circ}\text{C} \le T_A \le 85~^{\circ}\text{C}$, 3.0 V to 3.6 V and $-40~^{\circ}\text{C} \le T_A \le 85~^{\circ}\text{C}$, or 2.4 V to 3.0 V and $-40~^{\circ}\text{C} \le T_A \le 85~^{\circ}\text{C}$, respectively. Typical parameters are measured at 5 V, 3.3 V, and 2.7 V at 25 $^{\circ}\text{C}$ and are for design guidance only.

Table 42. 5-V AC External Clock Specifications

Symbol	Description	Min	Тур	Max	Units
F _{OSCEXT}	Frequency	0.093	_	24.6	MHz
_	High period	20.6	_	5300	ns
_	Low period	20.6	_	_	ns
_	Power-up IMO to switch	150	_	_	μS

Table 43. 3.3-V AC External Clock Specifications

Symbol	Description	Min	Тур	Max	Units
F _{OSCEXT}	Frequency with CPU clock divide by 1 ^[32]	0.093	_	12.3	MHz
F _{OSCEXT}	Frequency with CPU clock divide by 2 or greater ^[33]	0.186	_	24.6	MHz
_	High period with CPU clock divide by 1	41.7	_	5300	ns
_	Low period with CPU clock divide by 1	41.7	_	_	ns
_	Power-up IMO to switch	150	ı	_	μS

Notes

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^{32.} Maximum CPU frequency is 12 MHz at 3.3 V. With the CPU clock divider set to 1, the external clock must adhere to the maximum frequency and duty cycle requirements.

^{33.} If the frequency of the external clock is greater than 12 MHz, the CPU clock divider must be set to 2 or greater. In this case, the CPU clock divider ensures that the fifty percent duty cycle requirement is met



Table 44. 2.7-V AC External Clock Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
F _{OSCEXT}	Frequency with CPU clock divide by 1 ^[34]	0.093	_	12.3	MHz	
F _{OSCEXT}	Frequency with CPU clock divide by 2 or greater ^[35]	0.186	_	12.3	MHz	
_	High period with CPU clock divide by 1	41.7	_	5300	ns	
_	Low period with CPU clock divide by 1	41.7	-	-	ns	
_	Power-up IMO to switch	150	_	-	μs	

AC Programming Specifications

Table 45 lists the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and $-40~^{\circ}\text{C} \le T_{A} \le 85~^{\circ}\text{C}$, 3.0 V to 3.6 V and $-40~^{\circ}\text{C} \le T_{A} \le 85~^{\circ}\text{C}$, or 2.4 V to 3.0 V and $-40~^{\circ}\text{C} \le T_{A} \le 85~^{\circ}\text{C}$, respectively. Typical parameters are measured at 5 V, 3.3 V, and 2.7 V at 25 $^{\circ}\text{C}$ and are for design guidance only.

Table 45. AC Programming Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
t _{RSCLK}	Rise time of SCLK	1	_	20	ns	
t _{FSCLK}	Fall time of SCLK	1	_	20	ns	
t _{SSCLK}	Data setup time to falling edge of SCLK	40	_	_	ns	
t _{HSCLK}	Data hold time from falling edge of SCLK	40	_	-	ns	
F _{SCLK}	Frequency of SCLK	0	_	8	MHz	
t _{ERASEB}	Flash erase time (block)	_	20	_	ms	
t _{WRITE}	Flash block write time	_	80	-	ms	
t _{DSCLK}	Data out delay from falling edge of SCLK	_	_	45	ns	V _{DD} > 3.6
t _{DSCLK3}	Data out delay from falling edge of SCLK	_	_	50	ns	$3.0 \leq V_{DD} \leq 3.6$
t _{DSCLK2}	Data out delay from falling edge of SCLK	_	_	70	ns	$2.4 \leq V_{DD} \leq 3.0$
t _{ERASEALL}	Flash erase time (Bulk)	_	20	_	ms	Erase all blocks and protection fields at once
t _{PROGRAM_HOT}	Flash block erase + flash block write time	_	_	200 ^[36]	ms	0 °C ≤ Tj ≤ 100 °C
t _{PROGRAM_COLD}	Flash block erase + flash block write time	_	_	400 ^[36]	ms	$-40 ^{\circ}\text{C} \le \text{Tj} \le 0 ^{\circ}\text{C}$

Notes

^{34.} Maximum CPU frequency is 12 MHz at 3.3 V. With the CPU clock divider set to 1, the external clock must adhere to the maximum frequency and duty cycle requirements.

^{35.} If the frequency of the external clock is greater than 12 MHz, the CPU clock divider must be set to 2 or greater. In this case, the CPU clock divider ensures that the fifty percent duty cycle requirement is met.

^{36.} For the full industrial range, you must employ a temperature sensor user module (FlashTemp) and feed the result to the temperature argument before writing Refer to the Flash APIs application note Design Aids – Reading and Writing PSoC® Flash – AN2015 for more information.



Figure 20. 20-Pin (210-Mil) SSOP 1.14 DIA. PIN 1 ID. 10 1 1.14 7.50 8.10 DIMENSIONS IN MILLIMETERS MIN. MAX. 11 20 .235 MIN.- $\frac{7.00}{7.40}$ 0° MIN.-GAUGE PLANE 0.25 SEATING PLANE 0.65 BSC. <u>5.00</u> 5.60 0.-8. 2.00 1.65 1.85 0.55 1.25 REF. MAX 0.10 51-85077 *F

Figure 21. 20-Pin (300-Mil) Molded SOIC

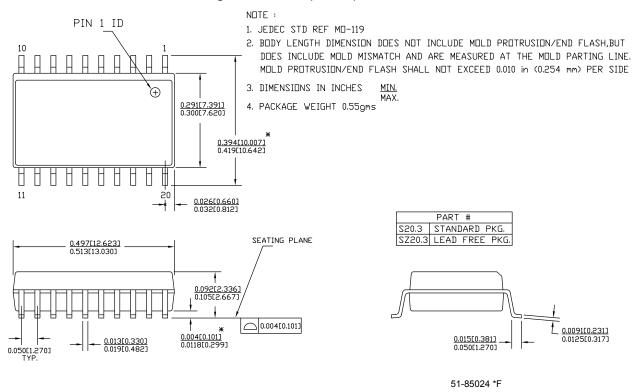




Figure 22. 28-Pin (300-Mil) Molded DIP

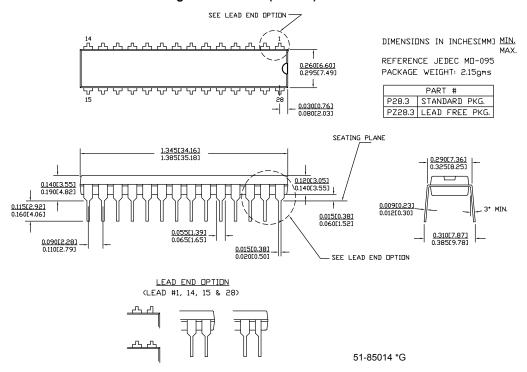
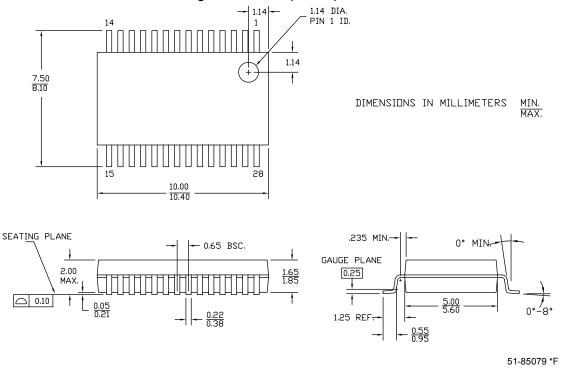


Figure 23. 28-Pin (210-Mil) SSOP



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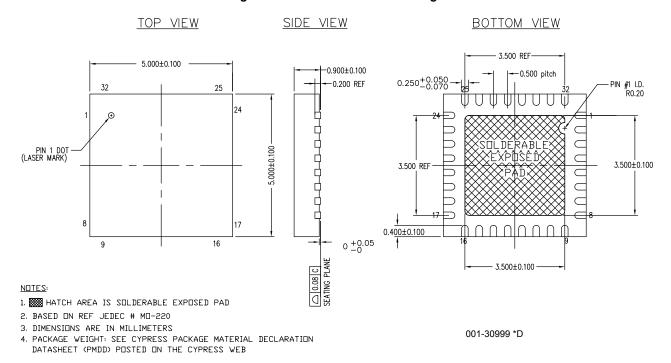
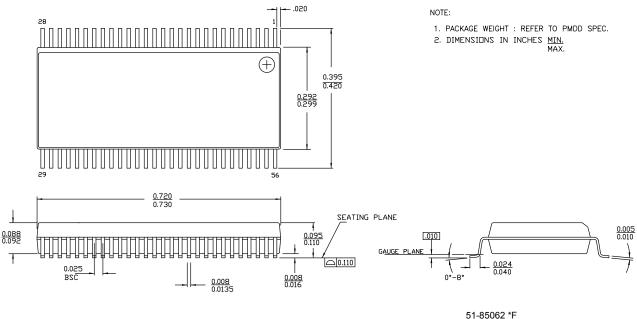


Figure 25. 32-Pin Sawn QFN Package

Important Note For information on the preferred dimensions for mounting QFN packages, see the application note, *Application Notes* for Surface Mount Assembly of Amkor's MicroLeadFrame (MLF) Packages available at http://www.amkor.com.

Figure 26. 56-Pin (300-Mil) SSOP



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Glossary (continued)

microcontroller An integrated circuit chip that is designed primarily for control systems and products. In addition to a CPU, a

microcontroller typically includes memory, timing circuits, and IO circuitry. The reason for this is to permit the realization of a controller with a minimal quantity of chips, thus achieving maximal possible miniaturization. This in turn, reduces the volume and the cost of the controller. The microcontroller is normally not used for

general-purpose computation as is a microprocessor.

mixed-signal The reference to a circuit containing both analog and digital techniques and components.

modulator A device that imposes a signal on a carrier.

noise 1. A disturbance that affects a signal and that may distort the information carried by the signal.

2. The random variations of one or more characteristics of any entity such as voltage, current, or data.

oscillator A circuit that may be crystal controlled and is used to generate a clock frequency.

parity A technique for testing transmitting data. Typically, a binary digit is added to the data to make the sum of all the

digits of the binary data either always even (even parity) or always odd (odd parity).

phase-locked loop (PLL)

An electronic circuit that controls an **oscillator** so that it maintains a constant phase angle relative to a reference

signal.

pinouts The pin number assignment: the relation between the logical inputs and outputs of the PSoC device and their

physical counterparts in the printed circuit board (PCB) package. Pinouts involve pin numbers as a link between

schematic and PCB design (both being computer generated files) and may also involve pin names.

port A group of pins, usually eight.

power on reset

(POR)

A circuit that forces the PSoC device to reset when the voltage is lower than a pre-set level. This is one type of

hardware reset.

PSoC[®] Cypress Semiconductor's PSoC[®] is a registered trademark and Programmable System-on-Chip™ is a trademark

of Cypress.

PSoC Designer™ The software for Cypress' Programmable System-on-Chip technology.

pulse width modulator (PWM)

An output in the form of duty cycle which varies as a function of the applied measurand

RAM An acronym for random access memory. A data-storage device from which data can be read out and new data

can be written in.

register A storage device with a specific capacity, such as a bit or byte.

reset A means of bringing a system back to a know state. See hardware reset and software reset.

ROM An acronym for read only memory. A data-storage device from which data can be read out, but new data cannot

be written in.

serial 1. Pertaining to a process in which all events occur one after the other.

2. Pertaining to the sequential or consecutive occurrence of two or more related activities in a single device or

channel.

settling time The time it takes for an output signal or value to stabilize after the input has changed from one value to another.



Errata

This section describes the errata for the CY8C24xxxA device family. Details include errata trigger conditions, scope of impact, available workaround, and silicon revision applicability. Contact your local Cypress Sales Representative if you have questions.

Part Numbers Affected

Part Number	Ordering Information
CY8C24123A	CY8C24123A-24PXI
	CY8C24123A-24SXI
	CY8C24123A-24SXIT
	CY8C24223A-24PXI
	CY8C24223A-24PVXI
	CY8C24223A-24PVXIT
	CY8C24223A-24SXI
	CY8C24223A-24SXIT
	CY8C24423A-24PXI
	CY8C24423A-24PVXI
	CY8C24423A-24PVXIT
	CY8C24423A-24SXI
	CY8C24423A-24SXIT
	CY8C24423A-24LFXI
	CY8C24423A-24LTXI
	CY8C24423A-24LTXIT
	CY8C24000A-24PVXI

CY8C24123A Qualification Status

Product Status: Production

CY8C24123A Errata Summary

The following table defines the errata applicability to available CY8C24123A family devices.

Items	Part Number	Silicon Revision	Fix Status
[1.]. Internal Main Oscillator (IMO) Tolerance Deviation at Temperature Extremes	CY8C24123A		No silicon fix planned. Workaround is required.

1. Internal Main Oscillator (IMO) Tolerance Deviation at Temperature Extremes

■ Problem Definition

Asynchronous Digital Communications Interfaces may fail framing beyond 0 to 70 $^{\circ}$ C. This problem does not affect end-product usage between 0 and 70 $^{\circ}$ C.

■ Parameters Affected

The IMO frequency tolerance. The worst case deviation when operated below 0° C and above +70 $^{\circ}$ C and within the upper and lower datasheet temperature range is $\pm 5\%$.

■ Trigger Condition(S)

The asynchronous Rx/Tx clock source IMO frequency tolerance may deviate beyond the data sheet limit of $\pm 2.5\%$ when operated beyond the temperature range of 0 to ± 70 °C.

■ Scope of Impact

This problem may affect UART, IrDA, and FSK implementations.

■ Workaround

Implement a quartz crystal stabilized clock source on at least one end of the asynchronous digital communications interface.

Fix Status

Silicon fix is not planned. The workaround mentioned above should be used.



Document History Page (continued)

Document Title: CY8C24123A/CY8C24223A/CY8C24423A, PSoC® Programmable System-on-Chip Document Number: 38-12028						
Revision	ECN	Orig. of Change	Submission Date	Description of Change		
*T	4066332	PMAD	07/17/2013	Added Errata Footnotes (Note 1, 19).		
				Updated PSoC Functional Overview: Updated PSoC Core: Added Note 1 and referred the same note in 4th paragraph in PSoC Core. Updated Electrical Specifications: Updated AC Electrical Characteristics: Updated AC Chip-Level Specifications: Added Note 19 and referred the same note in F _{IMO24} parameter. Updated minimum and maximum values of F _{IMO24} parameter.		
				Updated AC Digital Block Specifications: Replaced all instances of maximum value "49.2" with "50.4" and "24.6" with "25.2" in Table 37. Updated in new template.		
*U	4479672	RJVB	08/20/2014	Updated Packaging Information: Updated Packaging Dimensions: spec 51-85011 – Changed revision from *C to *D. spec 51-85024 – Changed revision from *E to *F. spec 51-85026 – Changed revision from *G to *H.		
				Updated Errata: Updated CY8C24123A Errata Summary: Updated details in "Fix Status" column in the table. Updated details in "Fix Status" bulleted point below the table. Completing Sunset Review.		
*V	4622083	RKRM	01/13/2015	Added More Information section.		



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